## **FDY6342L**

# **Integrated Load Switch**

## **General Description**

This device is particularly suited for compact power management in portable electronic equipment where 2.5 V to 8 V input and 0.83 A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) that drives a large P-Channel power MOSFET (Q2) in one tiny SC89-6 package.

#### **Features**

- Max  $r_{DS(on)} = 0.5 \Omega$  at  $V_{GS} = 4.5 \text{ V}$ ,  $I_D = -0.83 \text{ A}$
- Max  $r_{DS(on)} = 0.7 \Omega$  at  $V_{GS} = 2.5 \text{ V}$ ,  $I_D = -0.70 \text{ A}$
- Max  $r_{DS(on)} = 1.2 \Omega$  at  $V_{GS} = 1.8 \text{ V}$ ,  $I_D = -0.43 \text{ A}$
- Max  $r_{DS(on)} = 1.8 \Omega$  at  $V_{GS} = 1.5 \text{ V}$ ,  $I_D = -0.36 \text{ A}$
- Control MOSFET (Q1) Includes Zener Protection for ESD Ruggedness (>4 kV Human Body Model)
- High Performance Trench Technology for Extremely Low r<sub>DS(on)</sub>
- Compact Industry Standard SC89-6 Surface Mount Package
- This Device is Pb-Free and is RoHS Compliant

## **Applications**

- Power Management
- Load Switch

## MOSFET MAXIMUM RATINGS T<sub>A</sub> = 25°C Unless Otherwise Noted

Symbol	Parameter	Rating	Units
Vin	Gate to Source Voltage (Q2)	±8	٧
Von/off	Gate to Source Voltage (Q1)	–0.5 to 8	V
ILoad	Load Current -Continuous (Note 2)	0.83	Α
	-Pulsed (Note 2)	1.0	
$P_{D}$	Power Dissipation (Note 1a)	0.625	W
	Power Dissipation (Note 1b)	0.446	
TJ, TSTG	Operating and Storage Junction Temperature Range	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

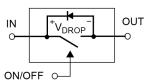
Symbol	Parameter	Rating	Units
R <sub>θ</sub> JA	Thermal Resistance, Junction to Ambient (Note 1a)	200	°C/W
Reja	Thermal Resistance, Junction to Ambient (Note 1b)	280	

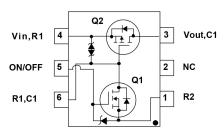


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#### **Equivalent Circuit**

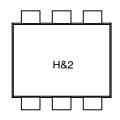




See Application Circuit



#### MARKING DIAGRAM



= Device Code (FDY6342L) 82 = Date Code (Year & Week)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

#### PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
Н	FDY6342L	SC89-6	7"	8 mm	3000 units

#### ELECTRICAL CHARACTERISTICS T. = 25°C, Unless Otherwise Noted

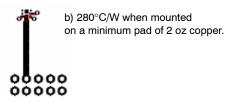
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
OFF CHAR	ACTERISTICS					
BV <sub>IN</sub>	V <sub>IN</sub> Breakdown Voltage	$I_D = -250 \mu A, V_{ON/OFF} = 0 V$	8			V
I <sub>Load</sub>	Zero Gate Voltage Drain Current	V <sub>IN</sub> = -6.4 V, V <sub>ON/OFF</sub> = 0 V			-1	μΑ
I <sub>FL</sub>	Leakage Current, Forward	V <sub>IN</sub> = 8 V, V <sub>ON/OFF</sub> = 0 V			10	μΑ
I <sub>RL</sub>	Leakage Current, Reverse	V <sub>IN</sub> = -8 V, V <sub>ON/OFF</sub> = 0 V			-10	μΑ
ON CHARA	CTERISTICS					
V <sub>ON/OFF(th)</sub>	Gate Threshold Voltage	$V_{IN} = V_{ON/OFF}$ , $I_D = -250 \mu A$	0.65	0.85	1.5	V
r <sub>DS(on)</sub>	Static Drain to Source On Resistance (Q2)	$V_{IN} = 4.5 \text{ V}, I_D = -0.83 \text{ A}$		0.28	0.5	Ω
		$V_{IN} = 2.5 \text{ V}, I_D = -0.70 \text{ A}$		0.35	0.7	
		$V_{IN} = 1.8 \text{ V}, I_D = -0.43 \text{ A}$		0.45	1.2	
		$V_{IN} = 1.5 \text{ V}, I_D = -0.36 \text{ A}$		0.57	1.8	
	Static Drain to Source On Resistance (Q1)	V <sub>IN</sub> = 4.5 V, I <sub>D</sub> = 0.4 A		2.9	4.0	
		$V_{IN} = 2.7 \text{ V}, I_D = 0.2 \text{ A}$		3.5	5.0	
DRAIN-SO	URCE DIODE CHARACTERISTICS					
I <sub>S</sub>	Maximum Continuous Drain to Source Diode	Forward Current			-0.25	Α
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>ON/OFF</sub> = 0 V, I <sub>S</sub> = -0.25 A (Note 2)		-0.8	-1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

R<sub>θJA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>θJC</sub> is guaranteed by design while R<sub>θJA</sub> is determined by the user's board design.

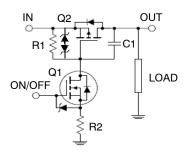


a) 200°C/W when mounted on a 1 in<sub>2</sub> pad of 2 oz copper.



2. Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%.

## FDY6342L Load Switch Application Circuit



#### External Component Recommendation:

For additional in-rush current control, R2 and C1 can be added. For more information, see application note AN1030.

## TYPICAL CHARACTERISTICS T<sub>J</sub> = 25°C, Unless Otherwise Noted

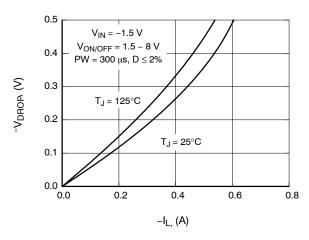


Figure 1. Conduction Voltage Drop Variation with Load Current

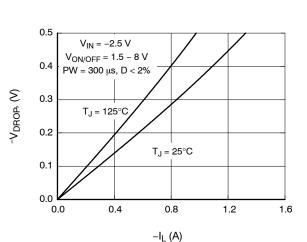


Figure 3. Conduction Voltage Drop Variation with Load Current

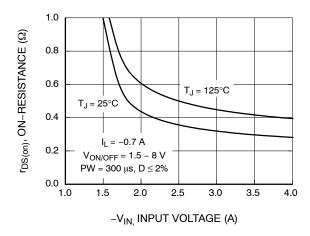


Figure 5. On-Resistance Variaton with Input Current

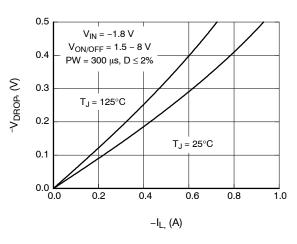


Figure 2. Conduction Voltage Drop Variation with Load Current

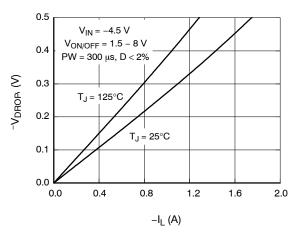


Figure 4. Conduction Voltage Drop Variation with Load Current

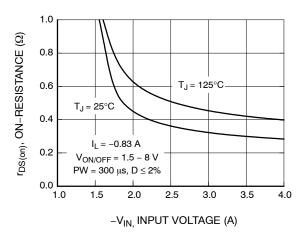
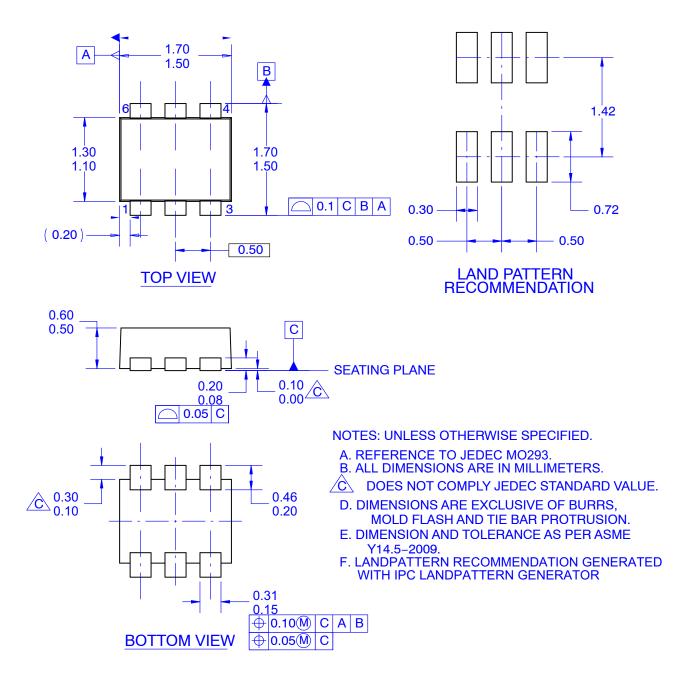


Figure 6. On–Resistance Variaton with Input Current



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